502729678 03/19/2014

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT2776284

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
STEVEN DOUGLAS LAVER	01/24/2014
XU GUO	01/24/2014
BRIAN MARC ROSENBERG	01/27/2014
DAVID MERRILL JACOBSON	02/21/2014

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14161185	

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Phone: (949) 681-8161

Email: qualcomm-pto@lozaip.com

Correspondent Name: LOZA & LOZA, LLP/QUALCOMM

Address Line 1: 305 N. SECOND AVE., #127 Address Line 4: UPLAND, CALIFORNIA 91786

ATTORNEY DOCKET NUMBER: QCOM-2360US (134318)	
NAME OF SUBMITTER:	JULIO LOZA
SIGNATURE:	/Julio Loza/
DATE SIGNED:	03/19/2014

Total Attachments: 9

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PATENT 502729678 REEL: 032478 FRAME: 0889



ASSIGNMENT

WHEREAS, WE,

- 1. Steven Douglas Laver, a citizen of Canada, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, California,
- 2. Xu Guo, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, California,
- 3. Brian Marc Rosenberg, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, California,
- 4. David Merrill Jacobson, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714 and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to KEY EXTRACTION DURING SECURE BOOT (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 14/161,185 filed January 22, 2014, Qualcomm Reference No. 134318, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

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REEL: 032478 FRAME: 0891

its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego,	on 1/24/2014	11/1 -
LOCATION	DATE	Steven Douglas Laver
Done at,	on	

PATENT QUALCOMM Ref. No. 134318 Page 3 of 3

LOCA	TION	DATE	Xu Guo	
Done atLOCA	on	DATE	Brian Marc Rosenberg	
Done at <u>Sau D; e</u> LOCA'	go, CA, on Fel	, 2(, 2014 DATE	David Merrill Jacobson	

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Done at		, on			
]	LOCATION		DATE	Steven Douglas Laver	

PATENT QUALCOMM Ref. No. 134318

Page 3 of 3

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Done at 🤇	5715 Morenaux A <u>CanDugo (A 92</u> 76h_	Jan. 24,2014	
	LOCATION	DATE	Xu Guo
Done at _	, on_		
	LOCATION	DATE	Brian Marc Rosenberg
Done at _	, on		
	LOCATION	DATE	David Merrill Jacobson

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Done at _		, on	
	LOCATION	DATE	Steven Douglas Laver
Done at $_$, on	

PATENT QUALCOMM Ref. No. 134318 Page 3 of 3

	LOCATION	DATE	Xu Guo
Done at	LOCATION	on <u>97 Jen 184</u> DATE	Rosenberg Brian Marc Rosenberg
Done at _	LOCATION	, on DATE	David Merrill Jacobson

PATENT REEL: 032478 FRAME: 0899

RECORDED: 03/19/2014